

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Stenson
#5/9
9-20-01

In re the Application of

Nobuaki HASHIMOTO

Application No.: US National Stage of PCT/JP00/06767

Filed: May 30, 2001

Docket No.: 109681

For: SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAME,
CIRCUIT BOARD, AND ELECTRONIC INSTRUMENT

PRELIMINARY AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D. C. 20231

Sir:

Prior to initial examination, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 7, 10, 17-19, 27 and 29 as follows:

7. (Amended) The semiconductor device as defined in claim 1,
wherein a recognition hole is formed in the substrate at a position differing from the
holes; and
wherein a recognition pattern is formed over the recognition hole on the side of a
surface of the substrate including the interconnecting pattern.

10. (Amended) The semiconductor device as defined in claim 1,
wherein the conductive members are a plurality of layered bumps.

17. (Amended) The semiconductor device as defined in claim 1,
wherein the semiconductor chip is mounted face-down to the substrate.

18. (Amended) A circuit board over which is mounted the semiconductor device
as defined in claim 1.